



SURFACE MOUNT SWITCHING DIODE

Features

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automated Insertion
- For General Purpose Switching Applications
- High Conductance
- Ultra Miniature Package
- Lead Free/RoHS Compliant (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- "Green" Device (Notes 4 and 5)

Mechanical Data

- Case: SOT-363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.006 grams (approximate)

SOT-363





TOP VIEW Internal Schematic

Maximum Ratings @T_A = 25°C unless otherwise specified

| Characteristic | | Symbol | Value | Unit |
|--|-----------------------|---------------------------------------|-------|------|
| Non-Repetitive Peak Reverse Voltage | | V_{RM} | 100 | V |
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | | V _{RRM} V _R wm | 75 | V |
| RMS Reverse Voltage | | V _{R(RMS)} | 53 | V |
| Forward Continuous Current | (Note 1) | I _{FM} | 500 | mA |
| Average Rectified Output Current | (Note 1) | Io | 250 | mA |
| Non-Repetitive Peak Forward Surge Current | @ t < 1μs @ t < 1s | I _{FSM} | 4 2 | А |

Thermal Characteristics

| Characteristic | | Symbol | Value | Unit |
|--|----------|-----------------------------------|-------------|------|
| Power Dissipation | (Note 1) | P_{D} | 200 | mW |
| Thermal Resistance Junction to Ambient Air | (Note 1) | $R_{	hetaJA}$ | 625 | °C/W |
| Operating and Storage Temperature Range | | T _J , T _{STG} | -65 to +150 | °C |

Electrical Characteristics @T_A = 25°C unless otherwise specified

| Characteristic | | Symbol | Min | Max | Unit | Test Condition | | |
|---------------------------|----------|--------------------|------|-------|------|--|----|---------------------------|
| Reverse Breakdown Voltage | (Note 2) | V _{(BR)R} | 75 | _ | V | $I_R = 10\mu A$ | | |
| | | | 0.62 | 0.720 | | $I_F = 5.0 \text{mA}$ | | |
| Forward Voltage | | V _F | _ | 0.855 | V | $I_F = 10 \text{mA}$ | | |
| l olward voltage | | | _ | 1.0 | V | $I_F = 50 \text{mA}$ | | |
| | | | | 1.25 | | I _F = 150mA | | |
| | (Note 2) | I _R | | 2.5 | μΑ | $V_R = 75V$ | | |
| Reverse Current | | | | 50 | μΑ | $V_R = 75V, T_J = 150$ °C | | |
| Neverse Current | | | чR | 'R | _ | 30 | μΑ | $V_R = 25V, T_J = 150$ °C |
| | | | | 25 | nA | $V_R = 20V$ | | |
| Total Capacitance | | C _T | _ | 4.0 | pF | $V_R = 0, f = 1.0MHz$ | | |
| Reverse Recovery Time | | | | 4.0 | ns | $I_F = I_R = 10 \text{mA},$ | | |
| Neverse Necovery Time | | t _{rr} | _ | | | $I_{rr} = 0.1 \text{ x } I_{R}, R_{L} = 100\Omega$ | | |

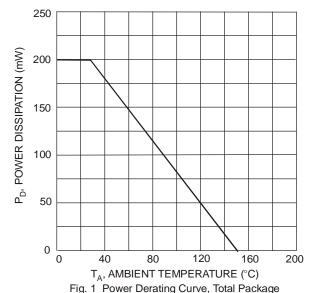
Notes:

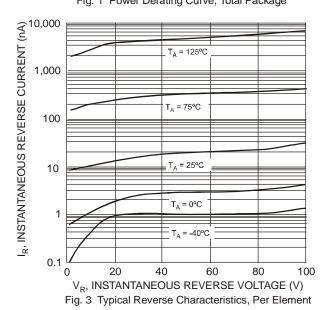
- 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- Short duration pulse test used to minimize self-heating.
- No purposefully added lead.
- Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
- Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

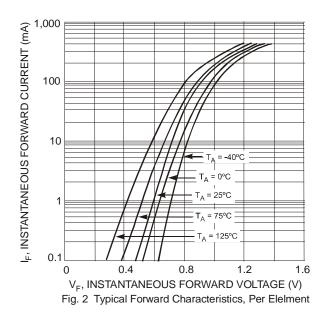
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MMBD4448DW









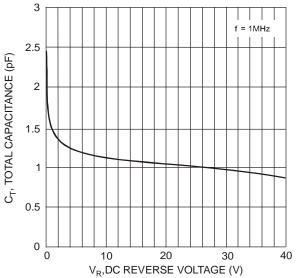


Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

Ordering Information (Note 6)

| Part Number | Case | Packaging |
|----------------|---------|------------------|
| MMBD4448DW-7-F | SOT-363 | 3000/Tape & Reel |

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



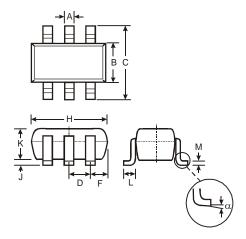
KA3 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: N = 2002) M = Month (ex: 9 = September)

Date Code Key

| Date Code Ney | | | | | | | | | | | | | | |
|---------------|------|------|------|------|------|------|-----|--------|----|------|------|------|------|------|
| Year | 2000 | 2001 | 2002 | 2003 | 2004 | 2005 | 200 | 06 200 | 07 | 2008 | 2009 | 2010 | 2011 | 2012 |
| Code | L | М | N | Р | R | S | Т | L | J | V | W | Х | Υ | Z |
| | | | | | | | | | | | _ | | | _ |
| Month | Jan | Feb | Mar | Apr | · Ma | ıy J | un | Jul | Αu | ıg | Sep | Oct | Nov | Dec |
| Code | 1 | 2 | 3 | 4 | 5 | | 6 | 7 | 8 | 3 | 9 | 0 | N | D |

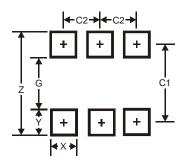


Package Outline Dimensions



| SOT-363 | | | | | | |
|----------------------|--------------------|------|--|--|--|--|
| Dim | Min | Max | | | | |
| Α | 0.10 | 0.30 | | | | |
| В | 1.15 | 1.35 | | | | |
| С | 2.00 | 2.20 | | | | |
| D | 0.65 | Тур | | | | |
| F | 0.40 | 0.45 | | | | |
| Н | 1.80 | 2.20 | | | | |
| J | 0 | 0.10 | | | | |
| K | K 0.90 1.00 | | | | | |
| L | _ 0.25 0.40 | | | | | |
| M | 0.10 | 0.22 | | | | |
| α | 0° | 8° | | | | |
| All Dimensions in mm | | | | | | |

Suggested Pad Layout



| Dimensions | Value (in mm) |
|------------|---------------|
| Z | 2.5 |
| G | 1.3 |
| Х | 0.42 |
| Y | 0.6 |
| C1 | 1.9 |
| C2 | 0.65 |

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